

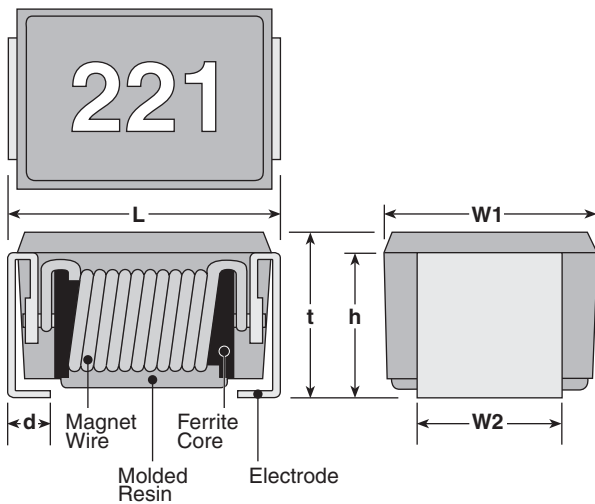


features

- UL94V0 molded epoxy case
- Suitable for reflow and wave soldering
- 1210 size - surface mount style
- High Q value achieved by wirewound structure
- Marking: Black body color with white marking
- Products with lead-free terminations meet EU RoHS requirements

Inductors

dimensions and construction



Type	Dimensions inches (mm)					
	L	W1	W2	t	h	d
KL32	.126±.008 (3.2±0.2)	.098±.008 (2.5±0.2)	.067±.004 (1.7±0.1)	.087±.008 (2.2±0.2)	.075±.004 (1.9±0.1)	.02 nominal (.5 nominal)

Inductance Marking

Value	Code
0.005μH - 0.082μH	005 - 082
0.10μH - 8.2μH	R10 - 8R2 R indicates decimal point.
10μH - 330μH	100 - 331 1st two figures are significant, the last figure indicates the number of zeros to follow.

ordering information

New Part #	KL	32	T	TE	101	J
Type			Termination Material	Packaging	Nominal Inductance	Tolerance
		Size	T: Sn	TE: 7" embossed plastic TED: 10" embossed plastic (TE: 2,000 pieces/reel) (TED: 4,000 pieces/reel)	Reference inductance marking chart	J: ±5% K: ±10% M: ±20%
		1210 size				

For further information on packaging, please refer to Appendix A.

applications and ratings

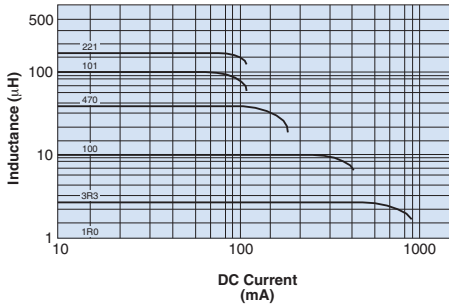
Part Designation	Inductance (μH)	Inductance Tolerance	Quality Factor Minimum	Self Resonant Frequency Minimum (MHz)	DC Resistance Maximum (Ω)	Allowable DC Current Maximum (mA)	Measured Frequency (MHz)
KL32TTE005*	0.005	M: ±20%	11	2700	0.12	450	100
KL32TTE010*	0.010	K: ±10% M: ±20%	15	2500	0.13		
KL32TTE012*	0.012		17	2300	0.14		
KL32TTE015*	0.015		19	2100	0.16		
KL32TTE018*	0.018		21	1900	0.18		
KL32TTE022*	0.022		23	1700	0.20		
KL32TTE027*	0.027		25	1500	0.22		
KL32TTE033*	0.033	J: ±5% K: ±10% M: ±20%	25	1400	0.24		
KL32TTE039*	0.039			1300	0.27		
KL32TTE047*	0.047			1200	0.30		
KL32TTE056*	0.056		26	1100	0.33		
KL32TTE068*	0.068			1000	0.36		
KL32TTE082*	0.082		27	900	0.40		
KL32TTER10*	0.10			700	0.44		
KL32TTER12*	0.12		J: ±5% K: ±10% M: ±20%	30	500		
KL32TTER15*	0.15				450	0.25	
KL32TTER18*	0.18				400	0.28	
KL32TTER22*	0.22				350	0.32	
KL32TTER27*	0.27				320	0.36	
KL32TTER33*	0.33				300	0.40	
KL32TTER39*	0.39				250	0.45	
KL32TTER47*	0.47				220	0.50	
KL32TTER56*	0.56	180			0.55		
KL32TTER68*	0.68	160			0.60		
KL32TTER82*	0.82	140			0.65		
KL32TTE1R0*	1.0	J: ±5% K: ±10% M: ±20%			30	120	0.70
KL32TTE1R2*	1.2					100	0.75
KL32TTE1R5*	1.5					85	0.85
KL32TTE1R8*	1.8					80	0.90
KL32TTE2R2*	2.2		75	1.0			
KL32TTE2R7*	2.7		70	1.1			
KL32TTE3R3*	3.3		60	1.2			
KL32TTE3R9*	3.9		55	1.3			
KL32TTE4R7*	4.7		50	1.5			
KL32TTE5R6*	5.6		47	1.6			
KL32TTE6R8*	6.8		43	1.8			
KL32TTE8R2*	8.2		40	2.0			
KL32TTE100*	10		36	2.1			
KL32TTE120*	12		33	2.5			
KL32TTE150*	15		30	2.8			
KL32TTE180*	18	27	3.3				
KL32TTE220*	22	25	3.7				
KL32TTE270*	27	20	5.0				
KL32TTE330*	33	17	5.6				
KL32TTE390*	39	16	6.4				
KL32TTE470*	47	15	7.0				
KL32TTE560*	56	13	8.0				
KL32TTE680*	68	12	9.0				
KL32TTE820*	82	11	10				
KL32TTE101*	100	20	10	10	45		
KL32TTE121*	120			11	70		
KL32TTE151*	150			8	15		
KL32TTE181*	180			7	17		
KL32TTE221*	220			6	21		
KL32TTE271*	270			5	28		
KL32TTE331*	330			5	34		

* Add tolerance character (J, K, M)

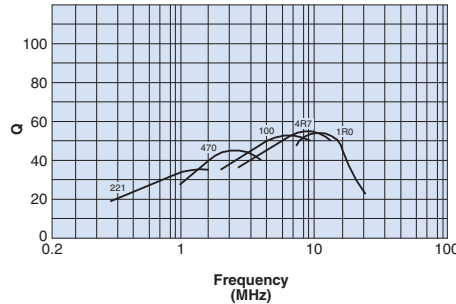
For complete environmental specifications, please refer to page 222.

environmental applications

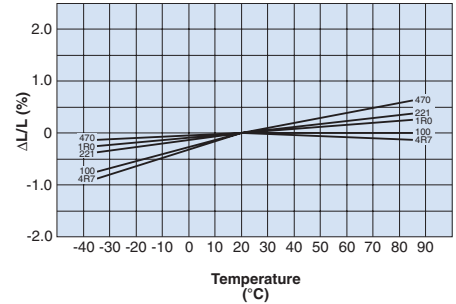
DC Current Characteristics



Q-Frequency Characteristics



Temperature Characteristics



Performance Characteristics

Parameter	Requirements Maximum Limit	Δ L/L Typical	Test Method
Resistance to Soldering Heat	Δ L/L: ±3%	Δ L/L: ±1.5%	260°C ± 5°C, 10s ± 1s
Heat Shock	Δ L/L: ±5%	Δ L/L: ±1.1%	-25°C (1 hour)/ +100°C (1 hour) 100 cycles
Low Temperature Operation	Δ L/L: ±5%, Δ Q/Q: ±20%	Δ L/L: ±0.9% Δ Q/Q: ±5.0%	-40°C ± 2°C, 1000h
High Temperature Exposure	Δ L/L: ±5%, Δ Q/Q: ±30%	Δ L/L: ±0.8% Δ Q/Q: ±5.0%	100°C ± 2°C, 1000h
Moisture Exposure	Δ L/L: ±5%, Δ Q/Q: ±30%	Δ L/L: ±1.3% Δ Q/Q: ±5.2%	40°C ± 2°C, 90%~95%RH, 1000h
Resistance to Solvent	No damage and marking shall be legible	—	Accordance with MIL-STD-202F Method 215

Inductors